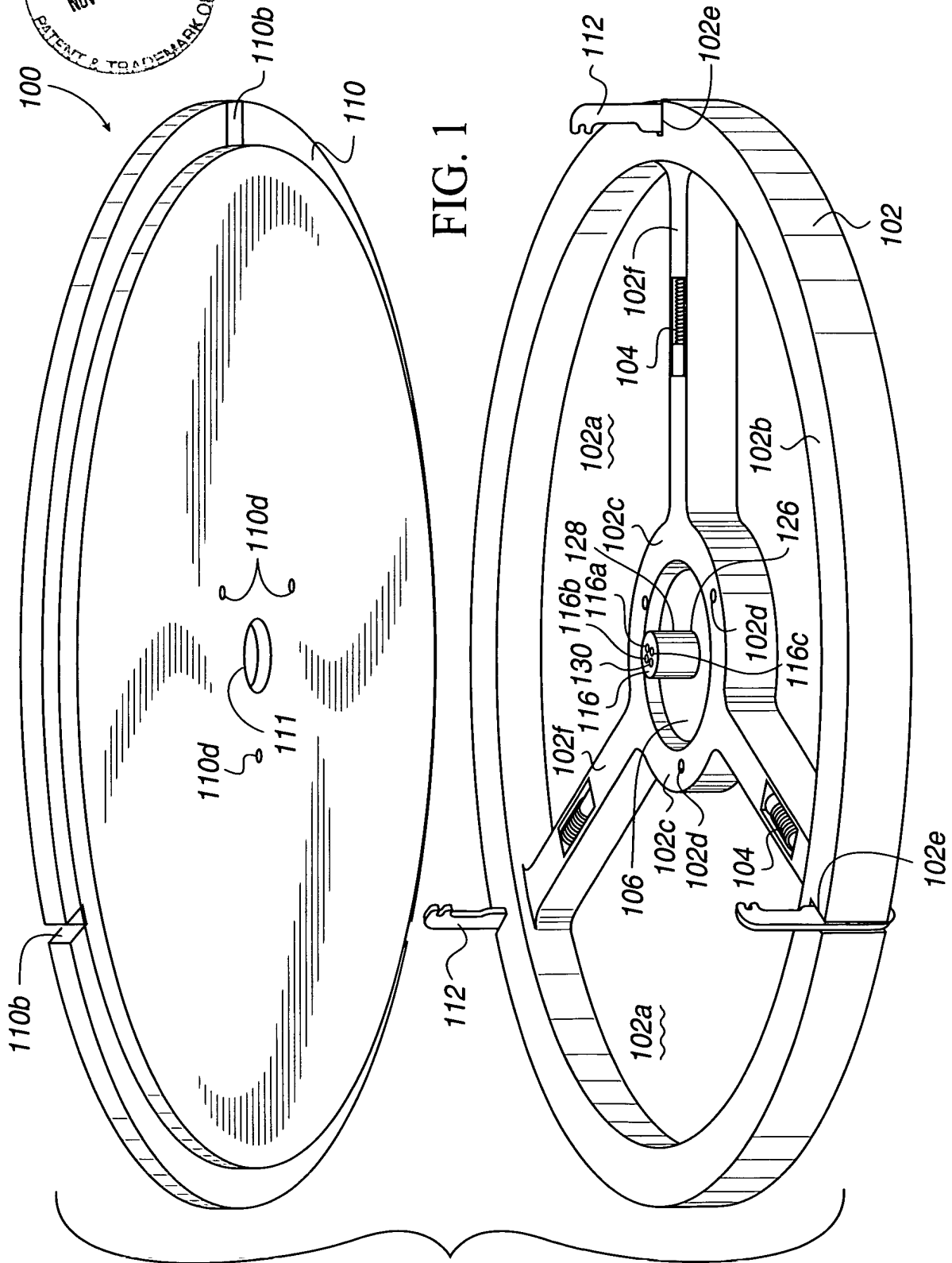
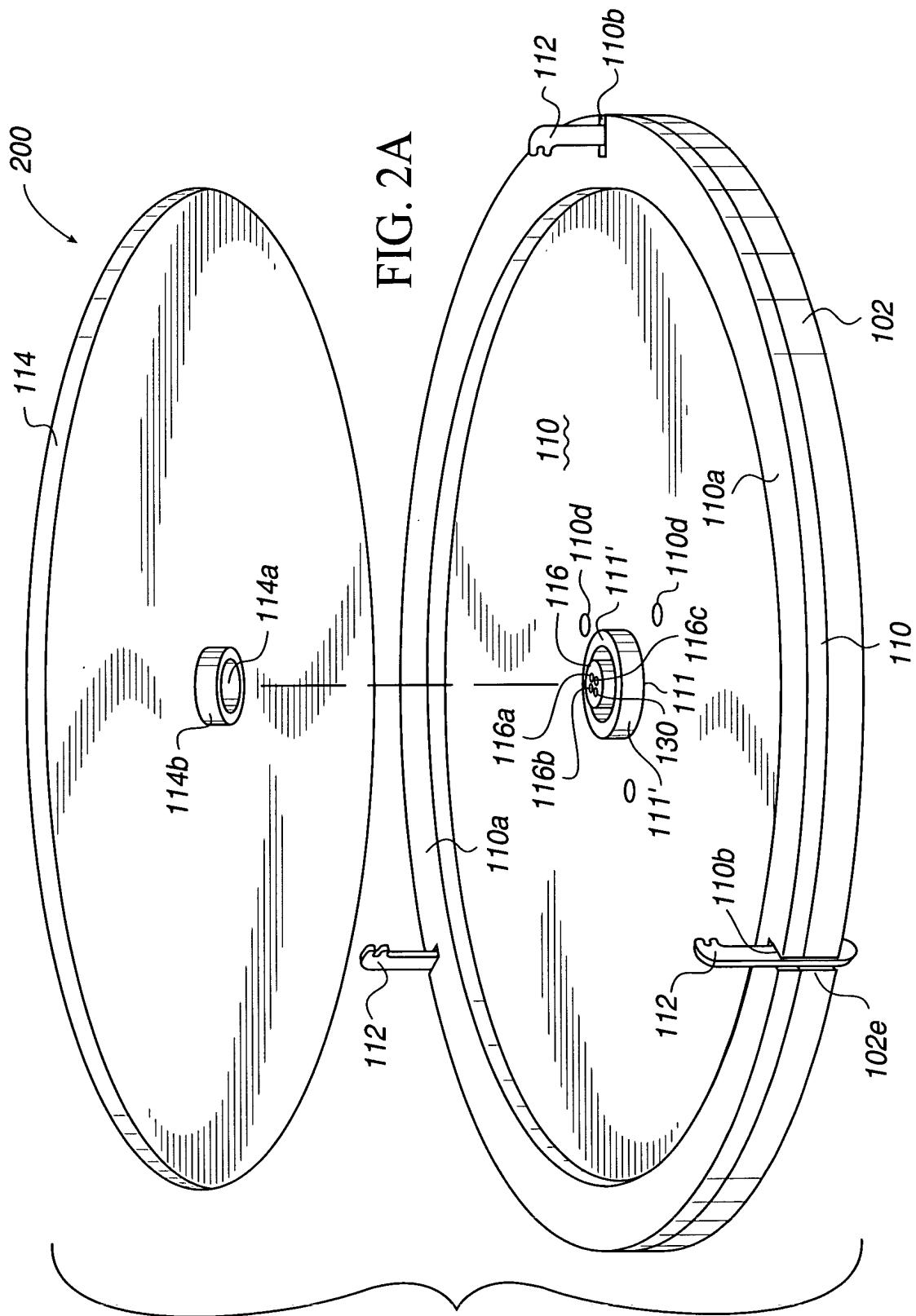
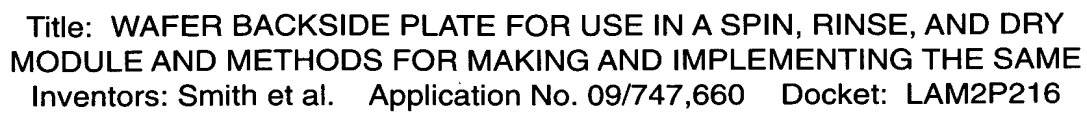
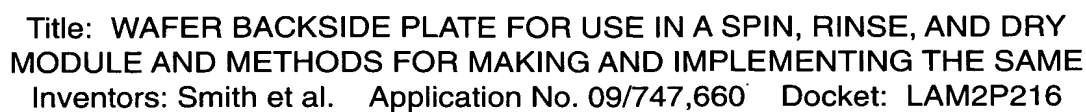


1 / 15







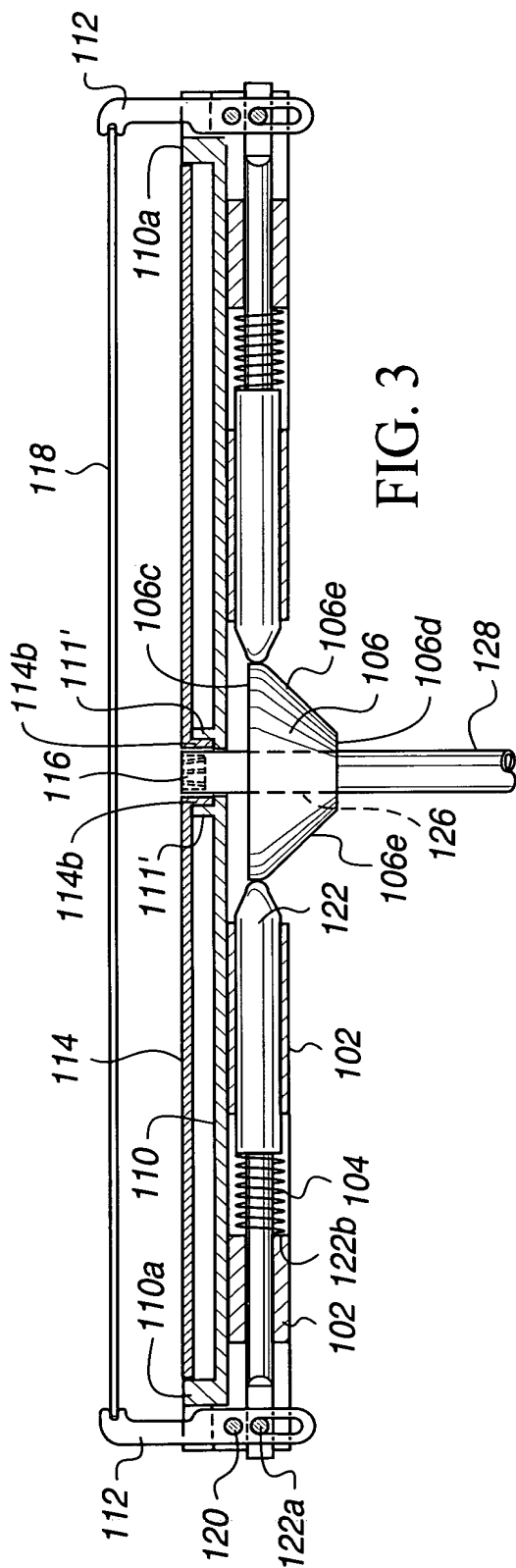


FIG. 3

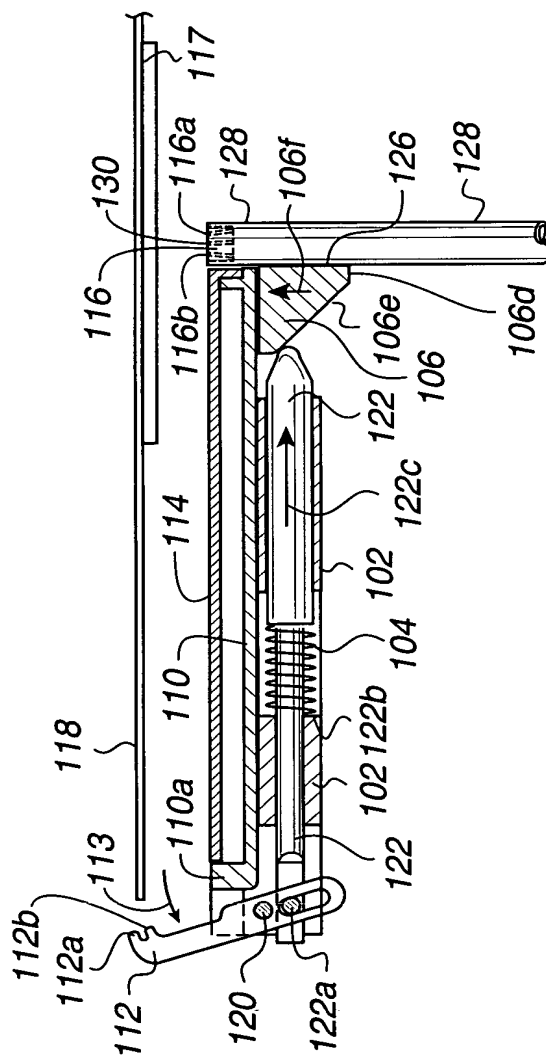
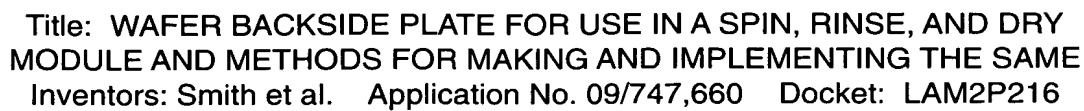
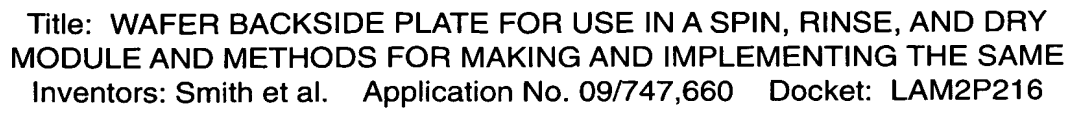


FIG. 4







7 / 15

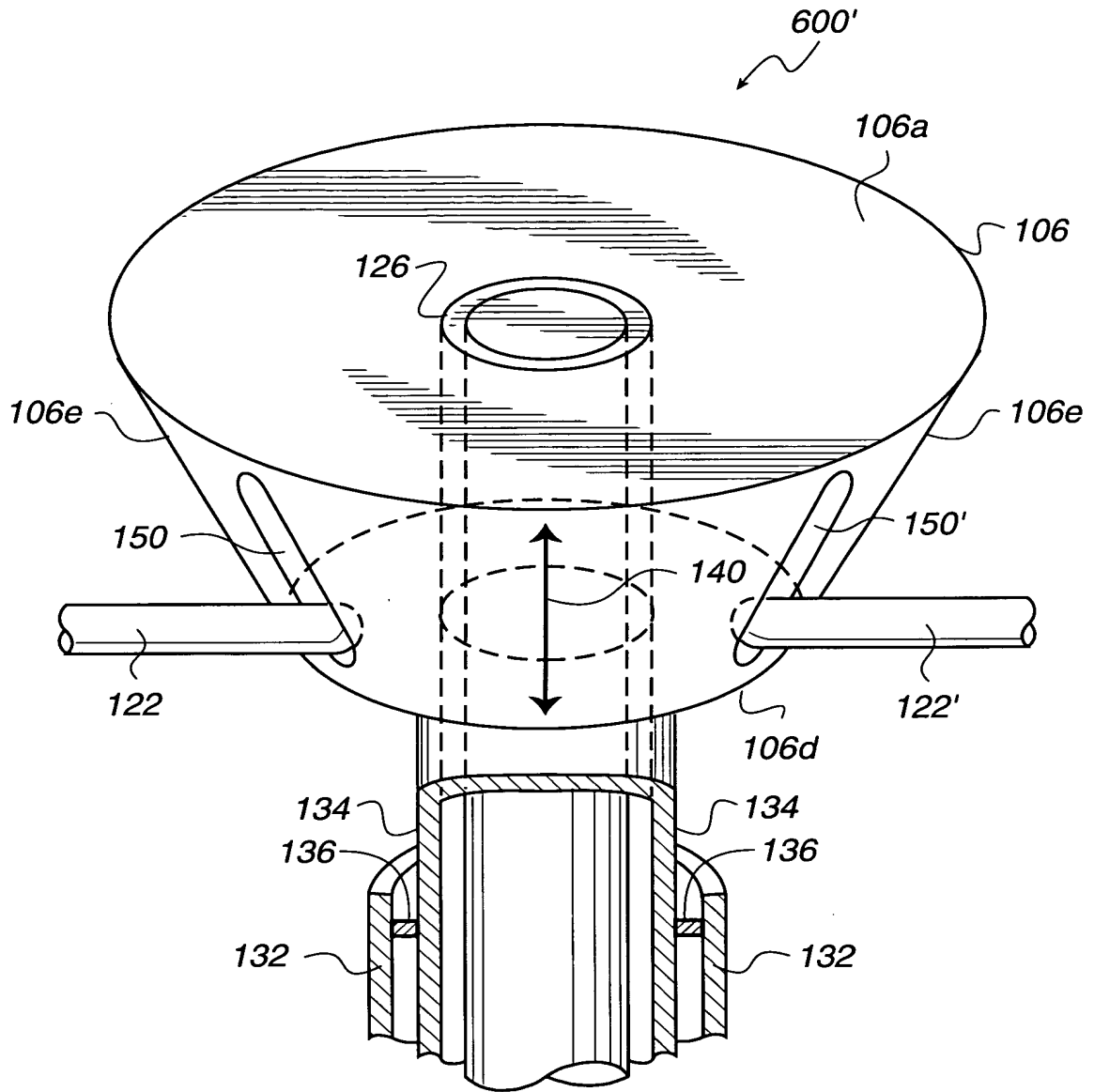


FIG. 6B

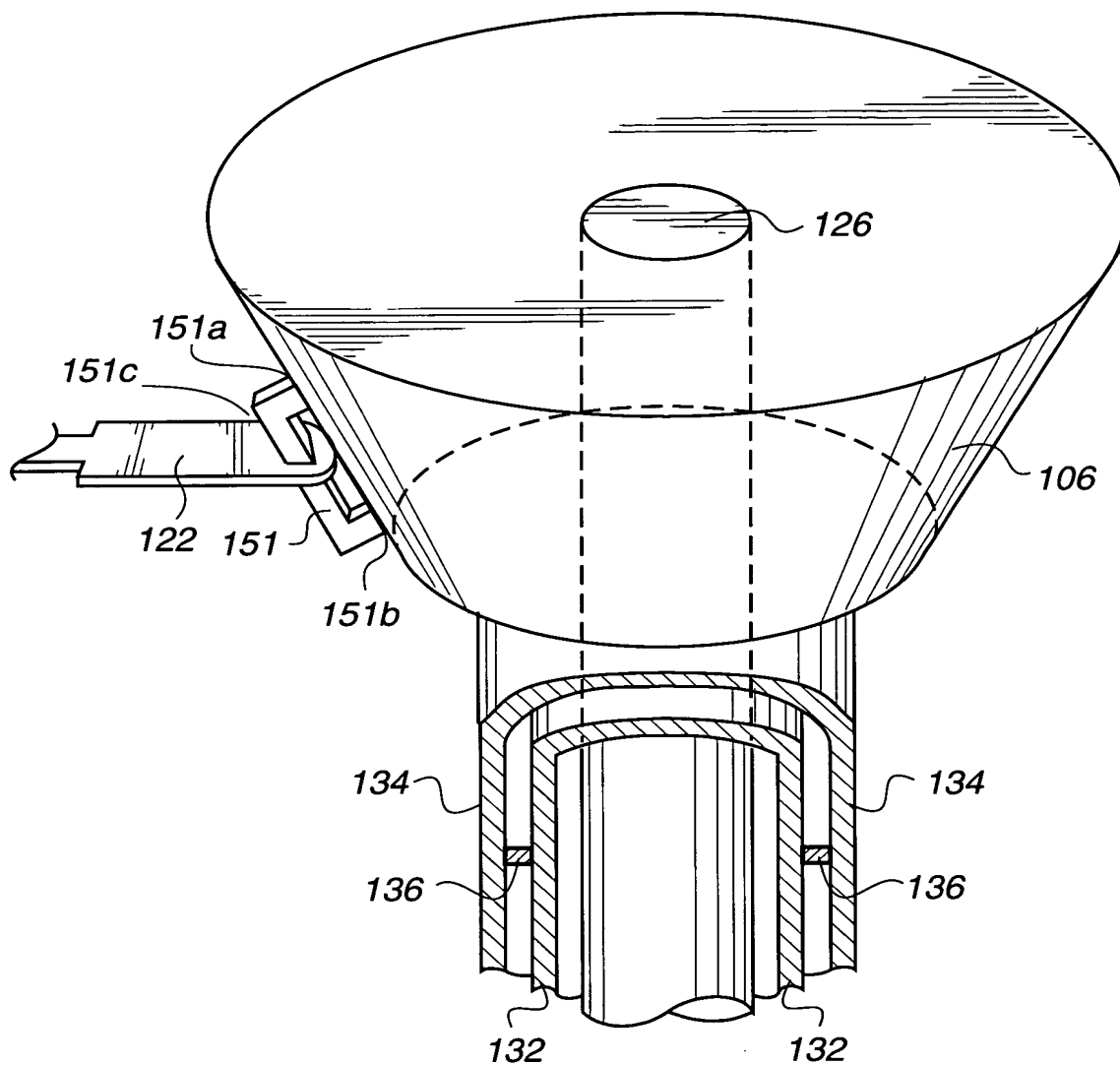
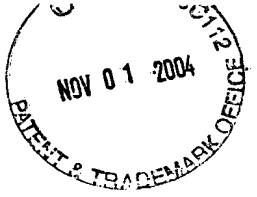


FIG. 6C



9 / 15

FIG. 7A

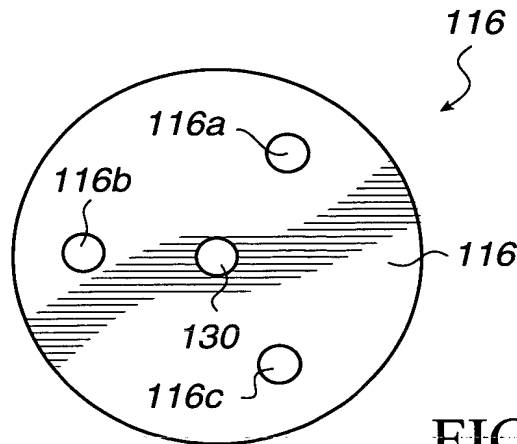
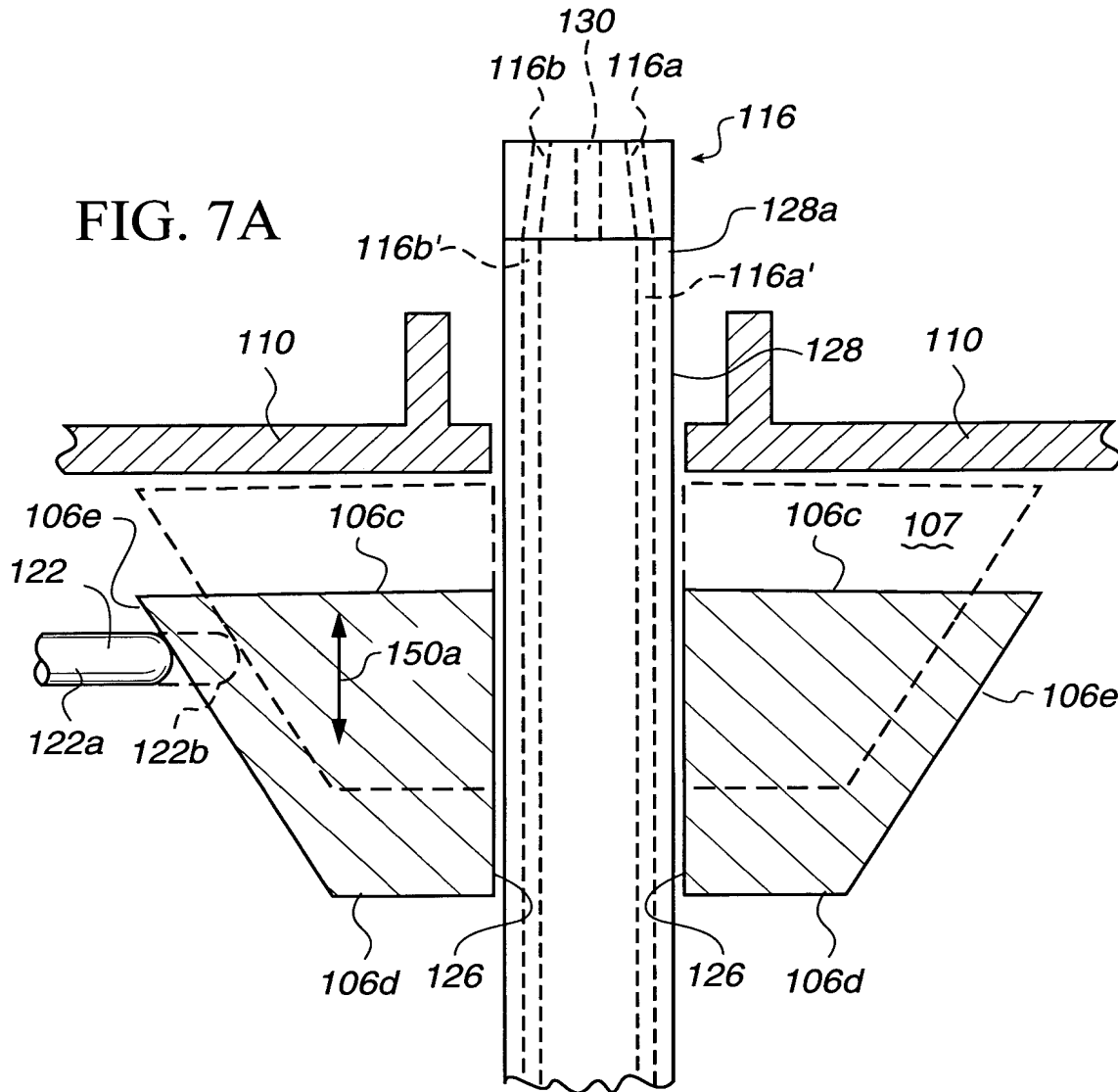
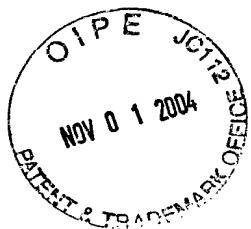


FIG. 7B



10 / 15

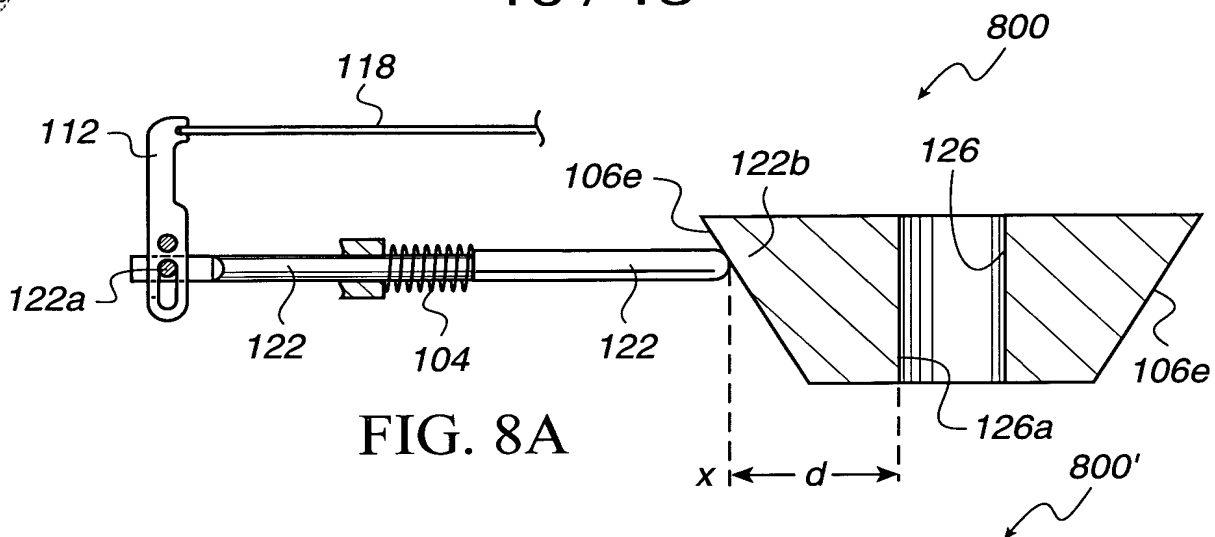


FIG. 8A

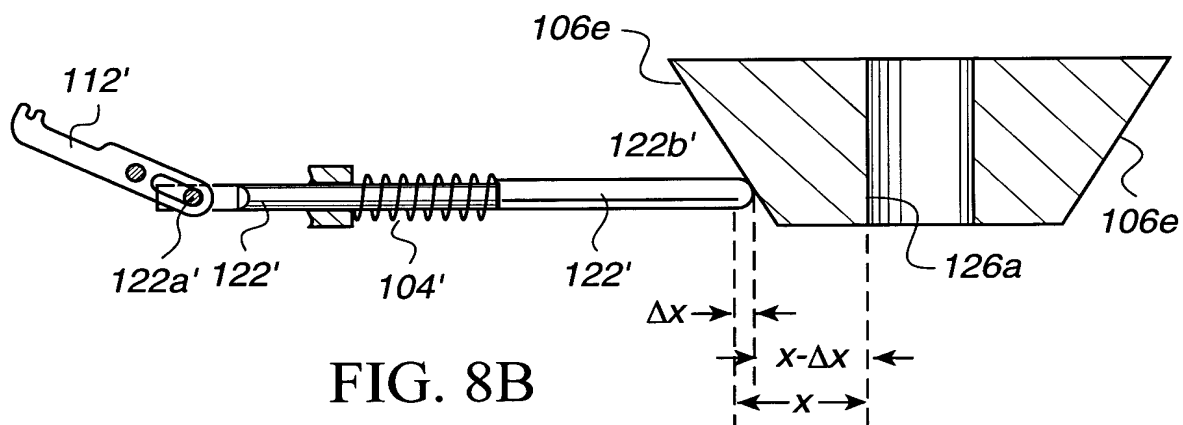


FIG. 8B

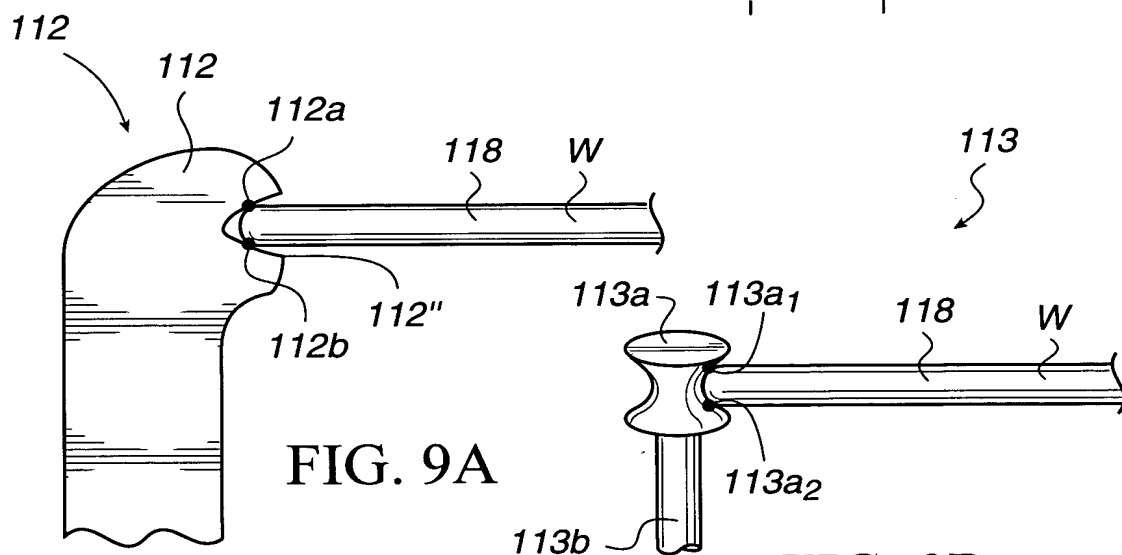


FIG. 9A

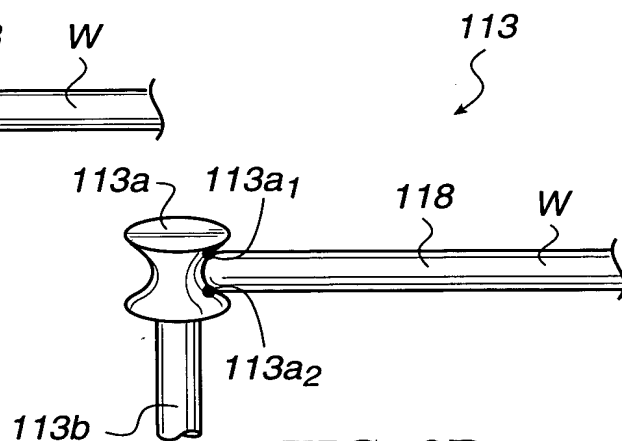
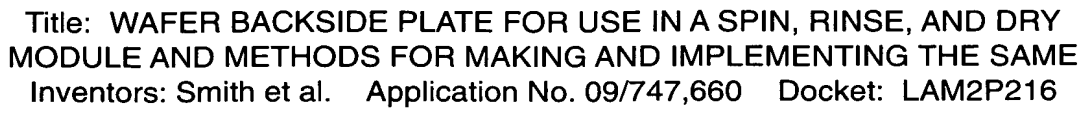
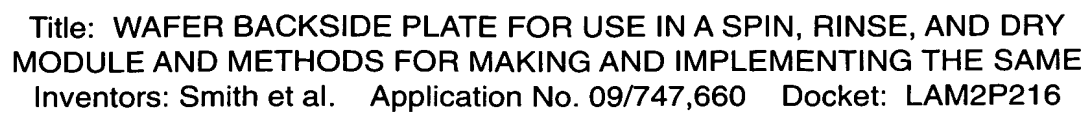


FIG. 9B









Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY  
MODULE AND METHODS FOR MAKING AND IMPLEMENTING THE SAME  
Inventors: Smith et al. Application No. 09/747,660 Docket: LAM2P216

14 / 15

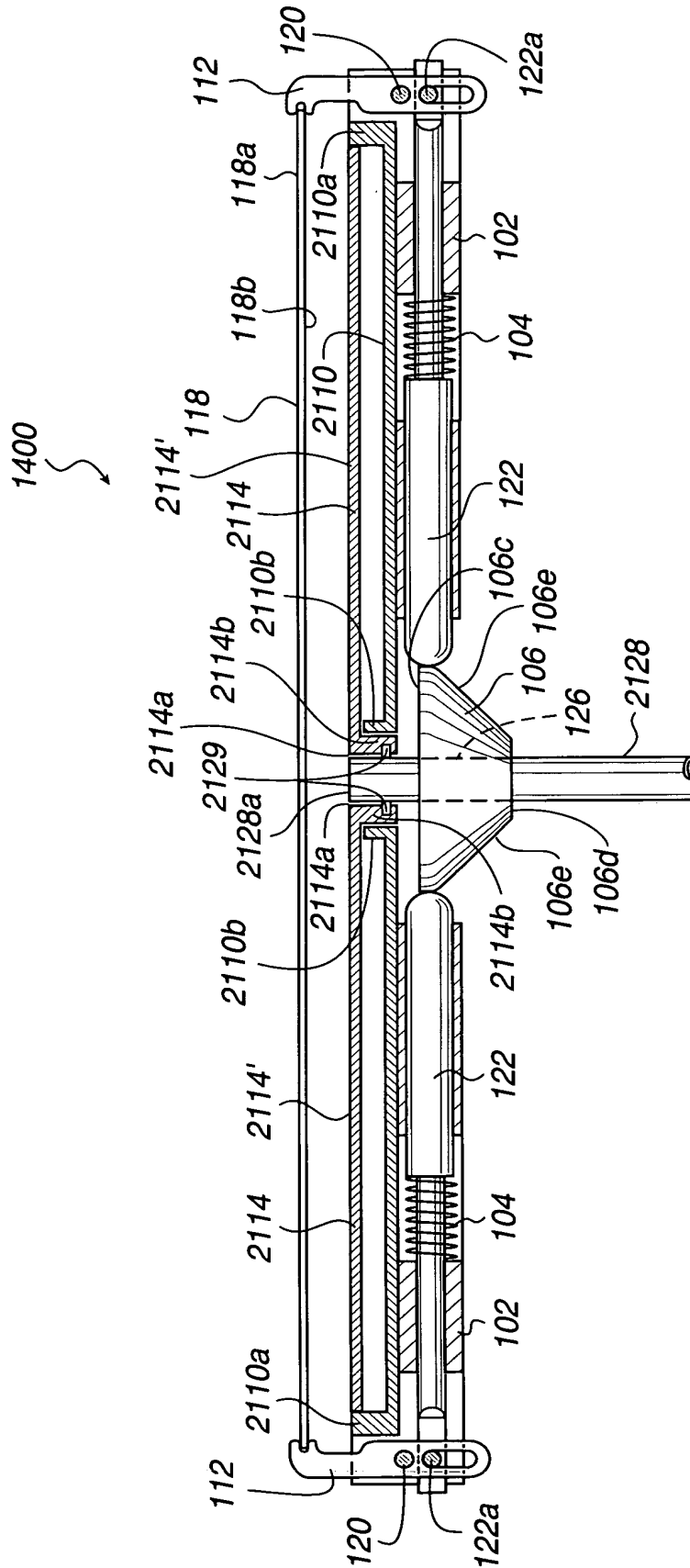


FIG. 14

